PCN Number:	20220615000.1	**PCN Date:**	June 16, 2022
Title:	Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, Datasheet update and additional Assembly site options for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Sep 16, 2022	**Sample requests accepted until:**	July 16, 2022*

***Sample requests received after July 16, 2022 will not be supported.**

Change Type:					
☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☒	Design	☒	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☒	Wafer Fab Materials	☒	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

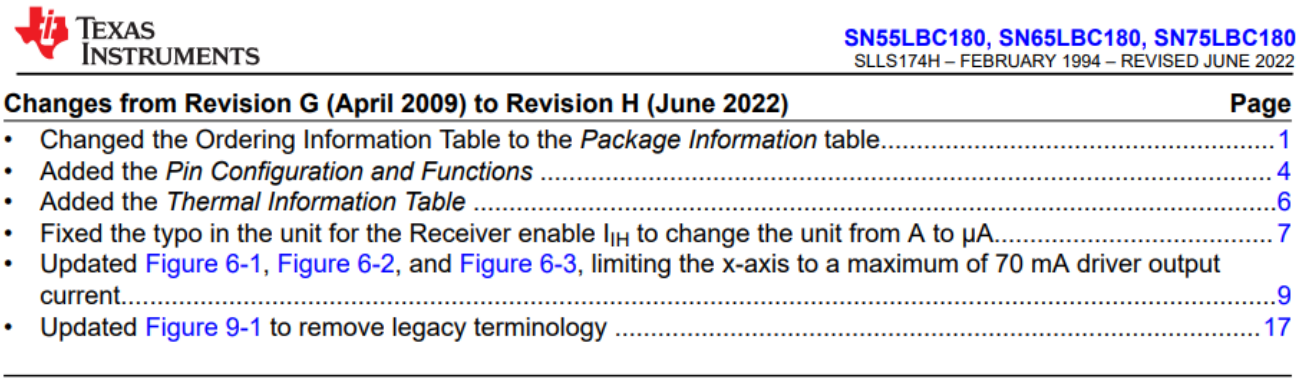
Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC7) and assembly site (MLA) options for selected devices as listed below in the product affected section.

Current Fab Site			New Fab Site		
Fab Site	**Process**	**Wafer Diameter**	**Fab Site**	**Process**	**Wafer Diameter**
DL-LIN	LBC2	150 mm	RFAB	LBC7	300 mm

The die was also changed as a result of the process change.

Construction Differences: No Material differences between assembly sites

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The link to the revised datasheet is available in the table below.



TEXAS INSTRUMENTS

SN55LBC180, SN65LBC180, SN75LBC180
SLLS174H – FEBRUARY 1994 – REVISED JUNE 2022

Changes from Revision G (April 2009) to Revision H (June 2022) **Page**

- Changed the Ordering Information Table to the *Package Information* table....1
- Added the *Pin Configuration and Functions* 4
- Added the *Thermal Information Table* 6
- Fixed the typo in the unit for the Receiver enable I_{IH} to change the unit from A to µA....7
- Updated Figure 6-1, Figure 6-2, and Figure 6-3, limiting the x-axis to a maximum of 70 mA driver output current....9
- Updated Figure 9-1 to remove legacy terminology 17

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN65LBC180	SLLS174G	SLLS174H	http://www.ti.com/product/SN55LBC180

Tube and temp versions of the devices are included in EOL notice PDN# 20220615001.3.

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A	**-**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
FMX	MEX	MEX	Aguascalientes
TI Malaysia	**MLA**	**MYS**	**Kuala Lumpur**

Sample product shipping label (not actual product label):

Product Affected:

SN65LBC180DR	SN65LBC180DRG4	

Qualification Report
Approve Date 10-May-2022

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65LBC180DR	QBS Process Reference: TPS51217DSC	QBS Process Reference: TPS51218DSC	QBS Package Reference: TCAN1043DQ1
AC	Autoclave 121C	96 Hours	-	6/462/0	-	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	3/9/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/60/0	1/20/0	1/30/0
HAST	Biased HAST 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
HBM	ESD – HBM(Bus pins)	12000 V	1/3/0	-	-	-
HBM	ESD – HBM (All pins)	4000 V	1/3/0	-	-	-
HTOL	Life Test, 135C	635 Hours	-	3/231/0	-	-
HTSL	High Temp Storage Bake 175C	500 Hours	-	-	-	1/45/0
LU	Latch-up	(Per JESD78)	1/6/0	3/18/0	-	-
MSL	Moisture Sensitivity, L1	L1-260C	1/12/0	-	-	-
PD	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0
SD	Surface Mount Solderability	PB Free Solder	-	-	-	1/15/0
SD	Surface Mount Solderability	PB Solder	-	-	-	1/15/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	3/231/0
WBP	Bond Pull	76 Wires, 3 units min	1/76/0	-	-	-
WBS	Ball Bond Shear	76 balls, 3 units min	1/76/0	-	-	3/90/0
YLD	Yield Evaluation	(per mfg. Site specification)	Pass	-	-	-

- QBS: Qual By Similarity
- Qual Device .SN65LBC180DR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com